

## Push Button Switch - PB 100

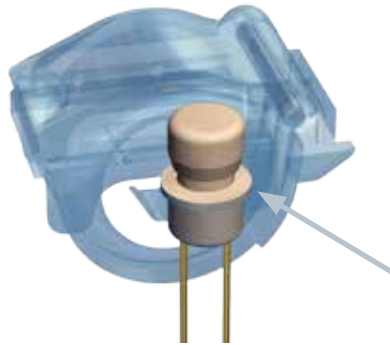
## 1. Introduction

Market requirements for smaller components size have led to the development of the PB 100, which has the following features:

- The diameter is only 1.9 mm (0.075") and the body height is just 1.4 mm (0.055"). This will allow the PB 100 to be built into ITCs where space is very limited, and perhaps even into CICs.
- By making the knob as large as the diameter of the housing and by increasing the friction of the knob surface, the PB 100 is easy to operate.
- Good resistance to soldering heat is achieved by choosing a high temperature resistant plastic material.
- At almost half the area of the existing push button PB 95, the new PB 100 is a major step forward in pursuing the continuing miniaturization at Sonion.

## 2. Handling

Handle PB 100 by the body to avoid mechanical stress to the leads.



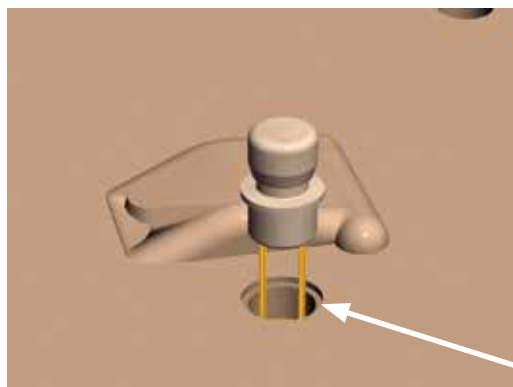
## 3. Tools

Proper tools should be used for cutting and bending, such as sharp cutters and soft-sided tweezers.



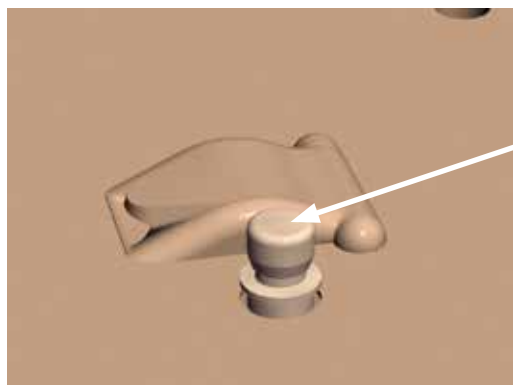
## 4. Mounting PB 100 into the faceplate (FP)

Diameter of the hole to fit the mechanical dimensions of PB 100.



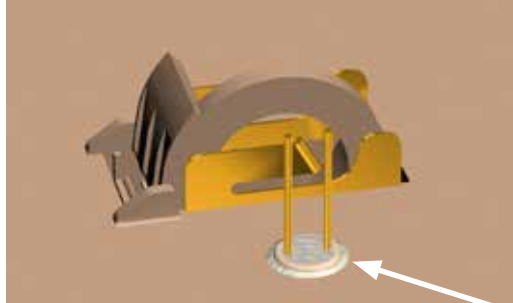
### b.

Carefully press on the top of the knob when inserting PB 100.



## 5. Gluing PB 100 for attachment to the FP

To attach PB 100 to the FP, add as little glue as possible into a ring around PB 100. Gluing PB 100 to the FP should be done before any handling of the leads.

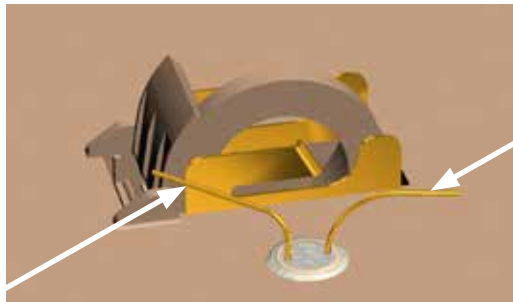


### Recommended glue types

Please refer to the Data Sheet. Use of other glue types (also including fumes from aggressive glues, may leave a non-conductive film on the contact surface.

## 6. Bending the leads

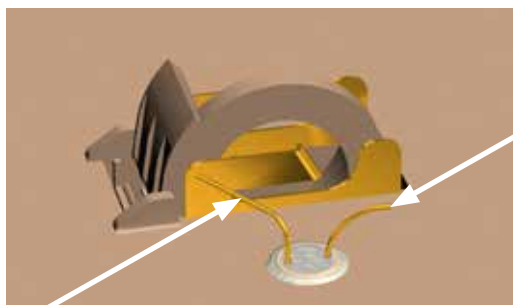
Leads must be bent before cutting. This will ensure a minimal of mechanical stress during the process. Minimum distance from housing is 0.5 mm (0.02"). Do not pull the leads while bending them.



### b.

Cut the leads before soldering

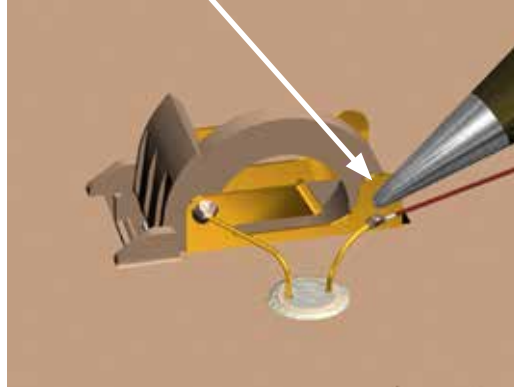
Cutting the leads should be done in one quick and steady operation. Avoid pulling/pushing the leads.



## 7. Soldering of leads

Please observe the soldering conditions given in the Technical Data Sheet. These include temperature, time, and distance to housing during soldering.

Avoid pressure on leads from solder-iron.



### b.

Avoid mechanical stress on the leads during, and 5 sec. after soldering, as this will otherwise damage the component.

If additional flux is necessary, we recommend that it is dispensed carefully and that the smallest amount possible is used. Due to the high alcohol content in some flux types the plastic parts may be damaged.

If flux residues are removed by using solvents or cleaning agents please observe the recommended process parameters given in the Data Sheet.

## 8. Cleaning

Flux residues may need to be removed by solvents, or cleaning agents. Please refer to the recommended cleaning solvents below:

- Aqua wash (Alpha 2110)
- Benzine

These cleaning solvents have been tested and proven not to degrade the plastic, or the resistance element. Use of any other solvents, or cleaning agents may be harmful to the resistance element, or the plastic (ref. data sheet on PB 100). We strongly advice against the use of any ultrasonic cleaning of the component.

## 9. General Operating Conditions

Please see our Data Sheet for other general operational conditions.